

**COMMODITY: SURFACE MOUNT LED SMD SPECIFICATION****Part No: 1SC3528W52F0WEC8****Characters**

- § 2.8mm×3.5mm SMT LED , 1.9mm THICKNESS.
- § LOW POWER CONSUMPTION.
- § VIEWING ANGLE 120°.
- § VARIOUS COLORS AND LENS TYPES AVAILABLE.
- § PACKAGE: 2000 PCS/REEL.

| ITEM | MATERIALS |
|---------------|-----------|
| Resin(Mold) | Silicone |
| Lens Color | Yellow |
| Dice | InGaN |
| Emitted color | White |

Absolute Maximum Ratings (Ta=25℃)

| Item | Symbol | Value | Unit |
|------------------------------------|--------|-------------|------|
| Power Dissipation/DICE | PD | 120 | mW |
| DC Forward Current/DICE | IF | 30 | mA |
| Single Chip Pulsed Forward Current | IFP | 100※ | mA |
| Reverse Voltage | VR | 5 | V |
| Operating Temperature | Topr | -30 ~ +80■ | ℃ |
| Storage Temperature | Tstg | -40 ~ +100 | ℃ |
| Soldering Temperature | Tsol | 260for5sec△ | ℃ |

※Duty 1/10, Pulse Width 0.1ms.

■please refer to IF-Ta diagram of curves for the temperature during application

△Soldering time max 10sec


Electrical-Optical Characteristics (Ta=25℃)

| Parameter | Symbol | Value | | | Unit | Test condition |
|-----------------------|--------|-------|--------|------|------|----------------|
| | | Min. | Typ. | Max. | | |
| Forward Voltage | Vf | 2.8 | 3.2 | 3.6 | V | If=20mA |
| Luminous intensity | Iv | 2050 | 2250 | 2650 | mcd | If=20mA |
| | Φv | 6.0 | 6.5 | 7.5 | Lm | |
| Wavelength | X | --- | 0.4403 | --- | --- | If=20mA |
| | y | --- | 0.4047 | --- | --- | If=20mA |
| Reverse Current | Ir | --- | --- | 10 | μA | Vr=5V |
| Viewing angle | 2θ 1/2 | --- | 120 | --- | Deg | If=20mA |
| Color Rendering Index | CRI | --- | 70 | --- | % | If=20mA |

1.Luminous intensity (IV) ±10%, Forward Voltage (VF) ±0.1V, Wavelength(X,Y) ±0.01
CRI±5%.

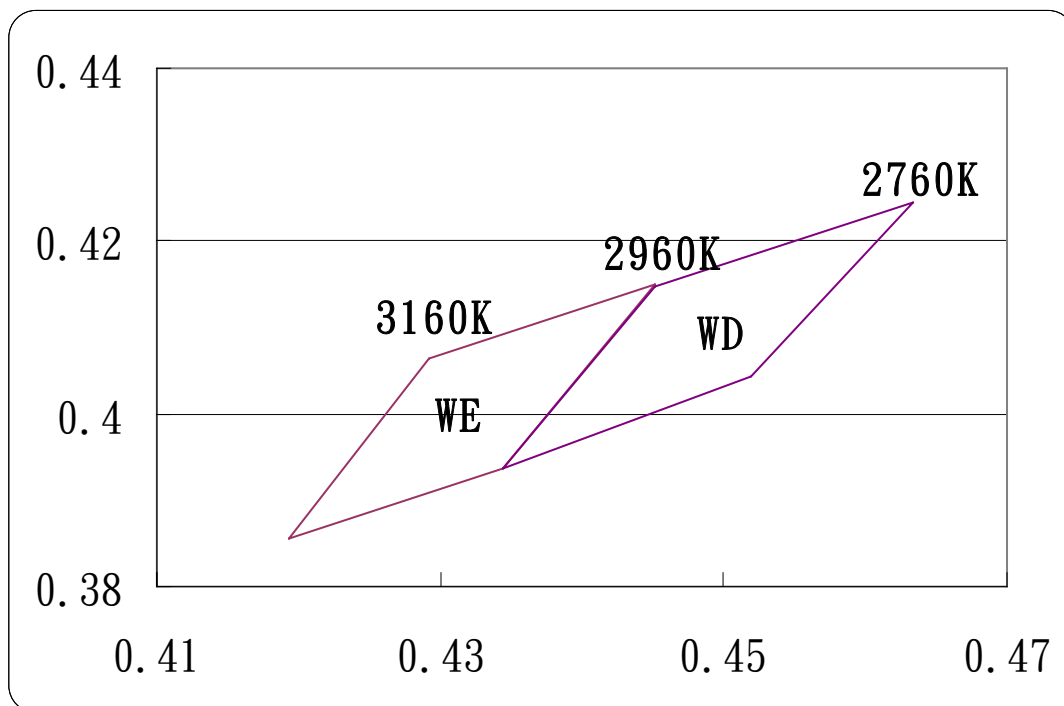
2.IS standard testing

Range of bins

| Bin | BinB | BinC | BinD | BinE | BinF | BinG | BinH |
|---------|-----------|-----------|-----------|---------|---------|---------|---------|
| VF(v) | 2.8-2.9 | 2.9-3.0 | 3.0-3.1 | 3.1-3.2 | 3.2-3.3 | 3.3-3.4 | 3.4-3.5 |
| Bin | BinI | | | | | | |
| VF(v) | 3.5-3.6 | | | | | | |
| Bin | Bin6 | Bin7 | Bin8 | | | | |
| Iv(mcd) | 2050-2250 | 2250-2450 | 2450-2650 | | | | |
| Bin | | | | | | | |
| WL(nm) | WD | WE | | | | | |



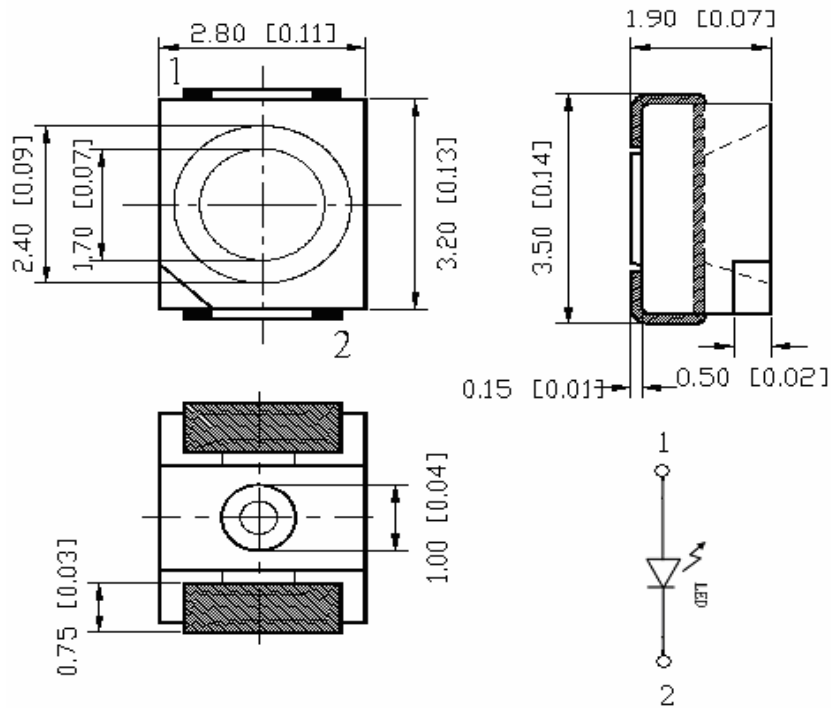
Color coordinate Comparison



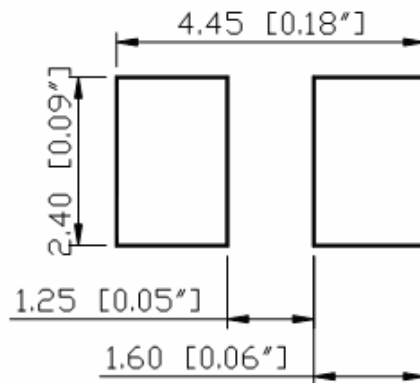
| Bin Code | X | Y | X | Y | X | Y | X | Y |
|----------|--------|--------|--------|--------|--------|--------|--------|--------|
| WE | 0.4292 | 0.4064 | 0.4193 | 0.3855 | 0.4344 | 0.3937 | 0.4451 | 0.4149 |
| WD | 0.4451 | 0.4147 | 0.4344 | 0.3937 | 0.4519 | 0.4044 | 0.4633 | 0.4245 |



Outline Dimensions



RECOMMEND PADLAYOUT



- § All dimensions are in millimeters(inch)
- § Tolerance is $\pm 0.1(0.004)$ ss other specified
- § Specifications are subject to change without notice.



COMMODITY: SURFACE MOUNT CHIP LED SMD SPECIFICATION

DEVICE NUMBER: **1SC3528W52F0WEC8**

Fig.1 IF-VF(Ta=25°C)

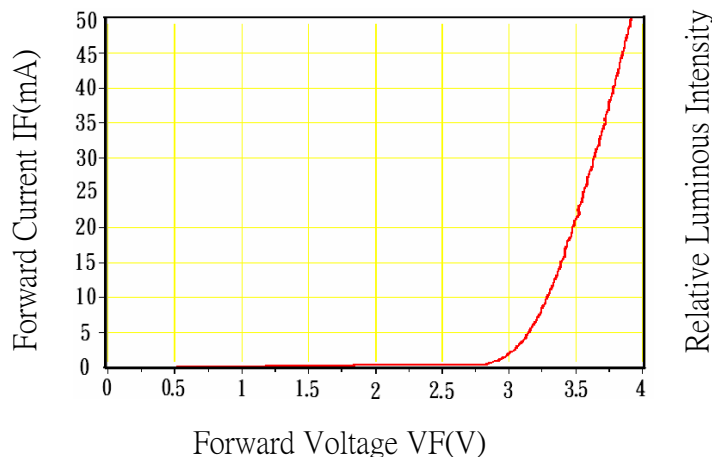


Fig.2 Relative Luminous Intensity-IF (Ta=25°C)

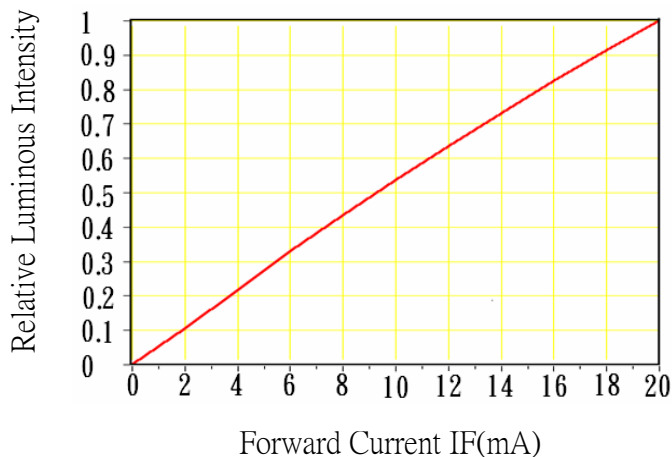


Fig.3 Wavelength Characteristics(Ta=25°C)

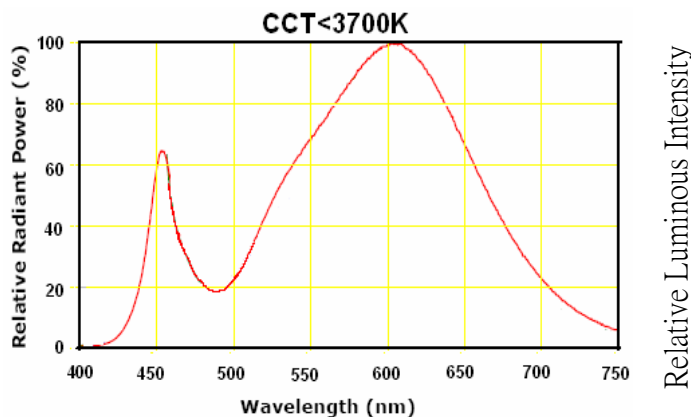


Fig.4 Relative Luminous Intensity-Ta

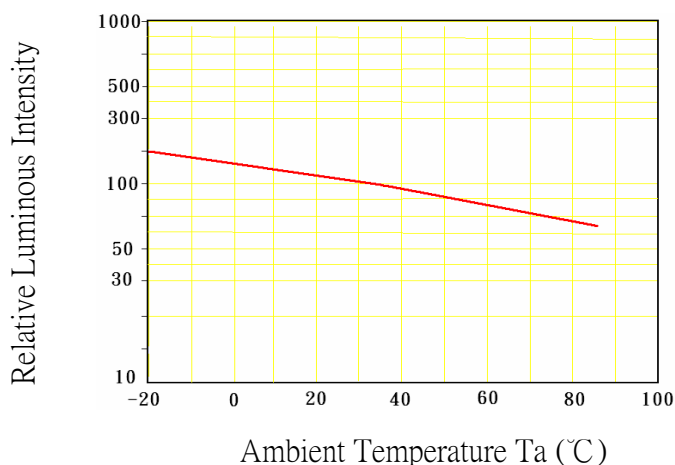
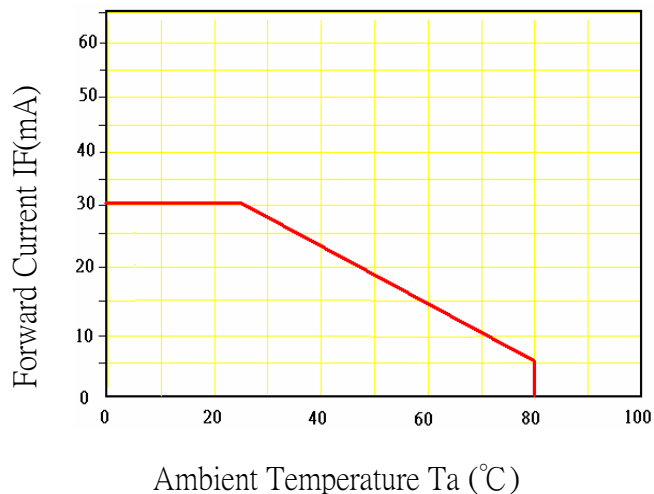
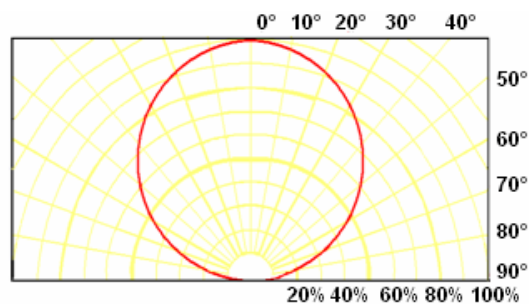


Fig.5 IF-Ta



Directive Characteristics (Ta=25°C)

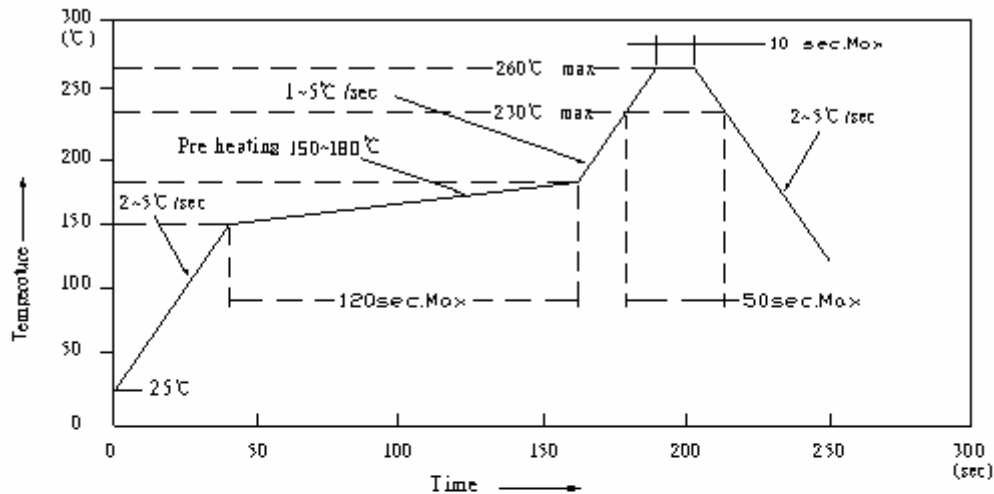




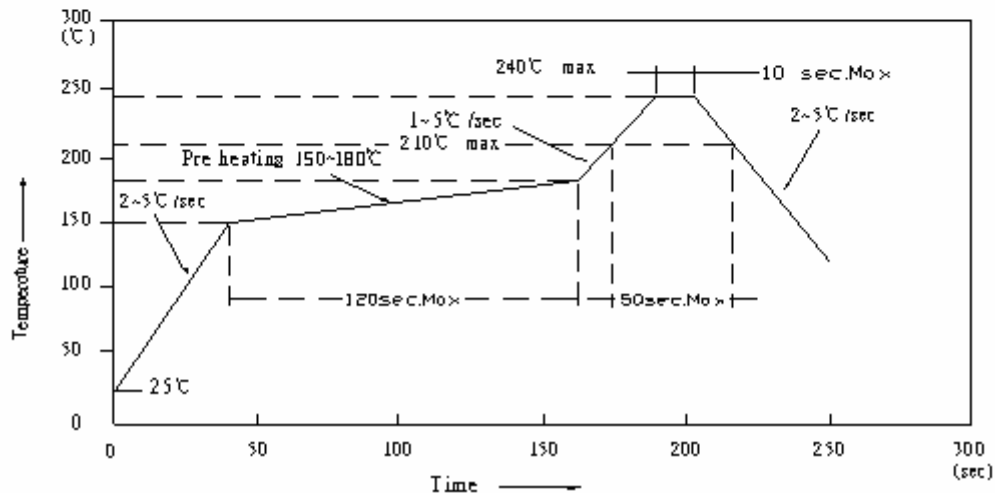
Reflow Profile

■ Reflow Temp/Time

IR Reflow Soldering Profile Lead Free Solder



IR Reflow Soldering Profile Lead Solder



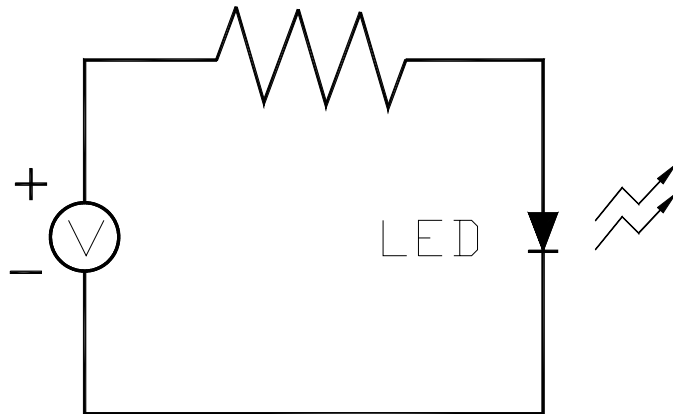
NOTES:

1. We recommend the reflow temperature 240°C (±5°C). the maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the silicone resin while it is exposed to high temperature.
3. Number of reflow process shall be 1 time.



Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C ~30°C (41°F ~86°F)

2.2 Shelf life in sealed bag: 12 month at <5°C ~30°C and <60% R.H. after the package is

Opened, the products should be used within a week or they should be keeping to stored at $\leq 20\%$ R.H. with zip-lock sealed.

3.Baking

It is recommended to baking before soldering when the pack is unsealed after 24hrs. The Conditions are as followings:

3.1 $70 \pm 3^\circ\text{C}$ x(12~24hrs) and <5%RH, taped reel type

3.2 $100 \pm 3^\circ\text{C}$ x(45min~1hr), bulk type

3.3 $130 \pm 3^\circ\text{C}$ x(15~30min), bulk type

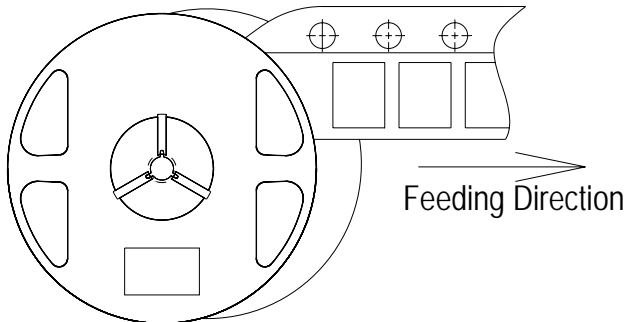
**Test items and results of reliability**

| Type | Test Item | Test Conditions | Note | Number of Damaged |
|------------------------|------------------------------|-----------------------------------------------|-----------|-------------------|
| Environmental Sequence | Temperature Cycle | -45°C 30min ↑ ↓ 20 min 105°C 30min | 100 cycle | 0/22 |
| | Thermal Shock | -10°C 15min ↑ ↓ 5sec 100°C 15min | 100 cycle | 0/22 |
| | High Humidity Heat Cycle | 30°C ⇔ 65°C 90%RH 24hrs/1cycle | 10 cycle | 0/22 |
| | High Temperature Storage | T _a =100°C | 1000 hrs | 0/22 |
| | Humidity Heat Storage | T _a =85°C RH=85% | 1000 hrs | 0/22 |
| | Low Temperature Storage | T _a =-40°C | 1000 hrs | 0/22 |
| Operation Sequence | Life Test | T _a =25°C I _F =20mA | 1000 hrs | 0/22 |
| | High Humidity Heat Life Test | 85°C RH=85% I _F =15mA | 500 hrs | 0/22 |
| | Low Temperature Life Test | T _a =-20°C I _F =20mA | 1000 hrs | 0/22 |

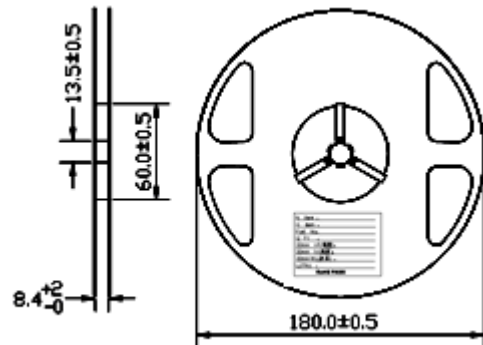


3528 Single-Color High Performance SMD Top LEDs Packaging Specifications

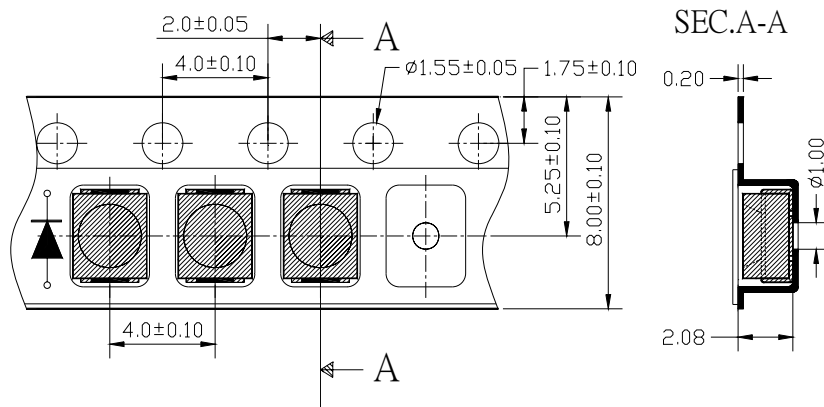
● Feeding Direction



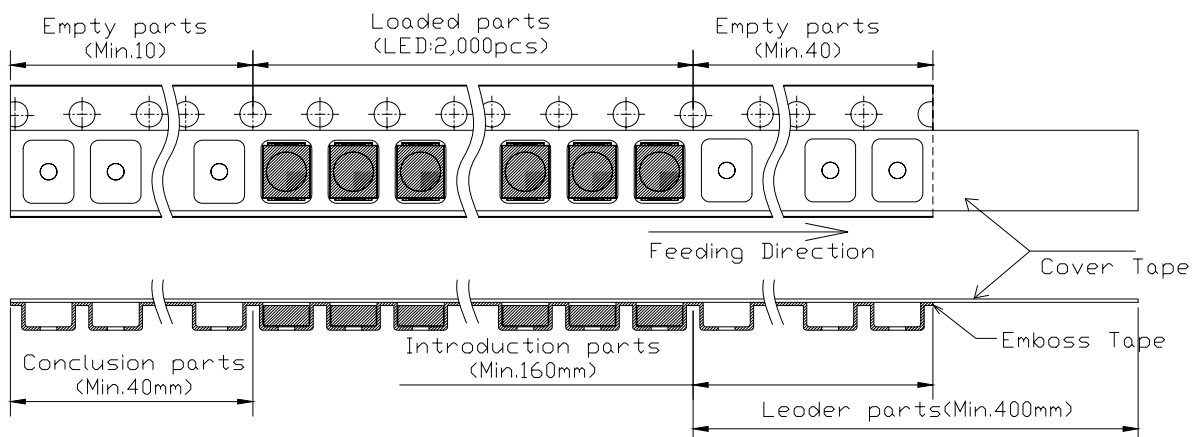
● Dimensions of Reel (Unit: mm)



● Dimensions of Tape (Unit: mm)



● Arrangement of Tape



NOTES

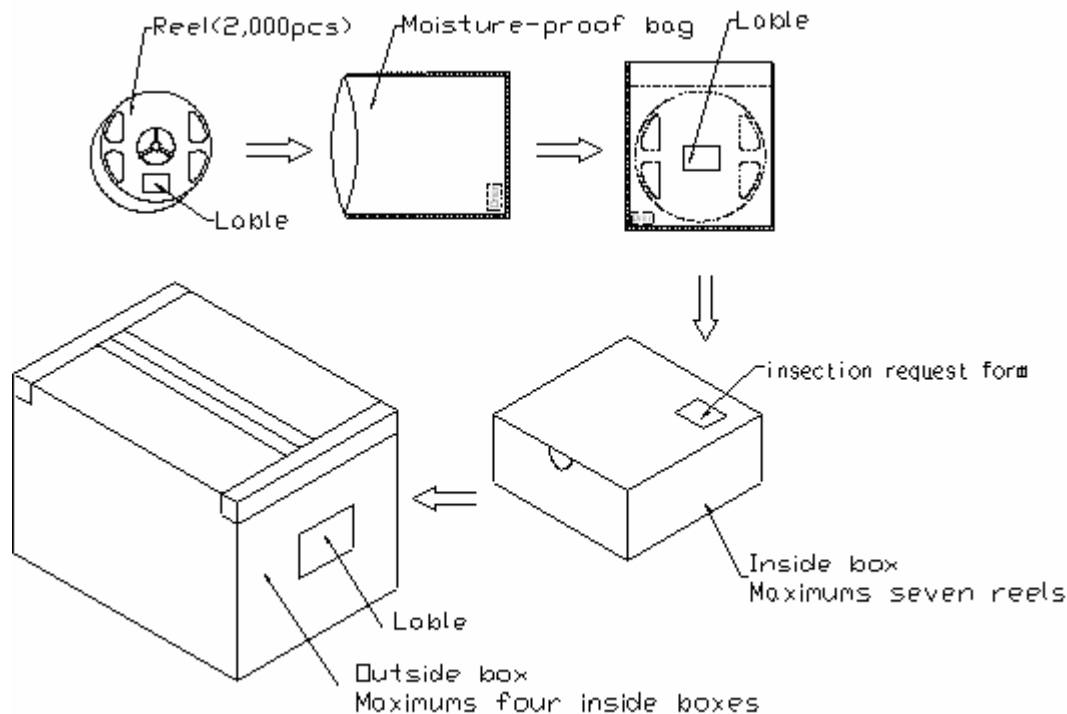
1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing smds is two;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications;

4. 2,000pcs/Reel



3528 Single-Color High Performance SMD Top LEDs Packaging Specifications

- Packaging specifications



NOTES:

Reeled products (The most numbers of products are 2,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, Seven moisture-proof bag of maximums (total maximum number of products are 14,000pcs) packed in an inside box (size: about 238mm x about 194mm x about 102mm) and four inside boxes of maximums are put in the outside box (size: about 410mm x about 254mm x about 229mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the insertion request form on the cardboard box.) .



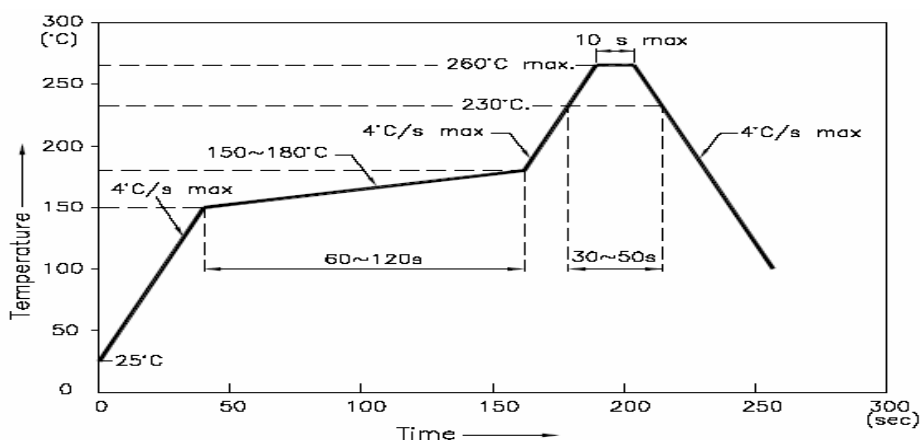
LED Usage and Handling Instructions

No.1 、soldering

A 、It's not better to be manual soldering.

B 、Reflow soldering :

1 、Soldering according to the following temperature chart is highly recommended



2 、Soldering paste

Use soldering paste with the melting point at 230°C is recommended

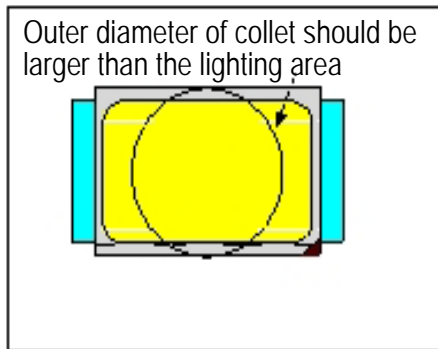
No.2 、Collet

1 、Abnormal situation caused by improper setting of collet

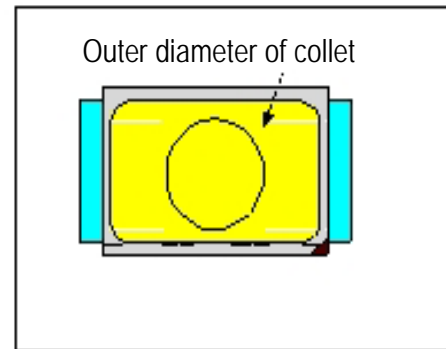
To choose the right collet is the key issue in improving the product's quality. LED is different from other electronic components, which is not only about electrical output but also for optical output. This characteristic made LED more fragile in the process of SMT. If the collet's lowering down height is not well set, it will bring damage to the gold wire at the time of collet's picking up and loading which will cause the LED fail to light up, light up now and then or other quality problems

2 、How to choose the collet

During SMT, please choose the collet that has larger outer diameter than the lighting area of lens, in case that improper position of collet will damage the gold wire inside the LED. Different collets fit for different products, please refer to the following pictures cross out:.



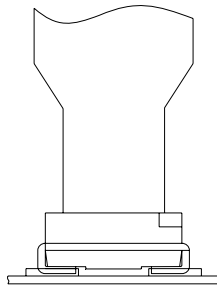
Picture 1 (✓)



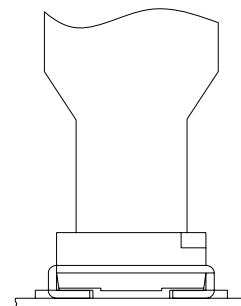
Picture 2 (✗)

3 、 How to set the height of collet

The reason why for top view SMD, the height of collet before it presses downward will directly affect the quality of products during SMT is that if the collect go down too much, it will press lens and cause the distortion or breaking of gold wire. The setting of collet position should follow the pictures belowed.



Picture 3 (✓)



Picture 4 (✗)

No.3 、 Other points for attention

- A 、 No pressure should be exerted to the epoxy shell of the SMD under high temperature.
- B 、 Do not scratch or wipe the lens since the lens and gold wire inside are rather fragile and cross out easy to break.
- C 、 LED should be used as soon as possible when being taken out of the original package, and should be stored in anti-moisture and anti-ESD package.

No.4 、 This usage and handling instruction is only for your reference.